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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	427200
Number of Logic Elements/Cells	1150000
Total RAM Bits	68857856
Number of I/O	624
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FCBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10at115u3f45e2sge2

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Feature		Description				
Embedded Hard IP blocks	Variable-precision DSP	 Native support for signal processing precision levels from 18 x 19 to 54 x 54 Native support for 27 x 27 multiplier mode 64-bit accumulator and cascade for systolic finite impulse responses (FIRs) Internal coefficient memory banks Preadder/subtractor for improved efficiency Additional pipeline register to increase performance and reduce power Supports floating point arithmetic: Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication. Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability. Dynamic accumulator reset control. Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks. 				
	Memory controller	DDR4, DDR3, and DDR3L				
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port				
	Transceiver I/O	10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC) PCS hard IPs that support:				
Core clock networks	 667 MHz externa 800 MHz LVDS in Global, regional, and 	c clocking, depending on the application: I memory interface clocking with 2,400 Mbps DDR4 interface terface clocking with 1,600 Mbps LVDS interface I peripheral clock networks are not used can be gated to reduce dynamic power				
Phase-locked loops (PLLs)	 Support integer r Fractional mode s Integer PLLs: Adjacent to gene 	rnthesis, clock delay compensation, and zero delay buffering (ZDB) mode and fractional mode support with third-order delta-sigma modulation				
FPGA General-purpose I/Os (GPIOs)	On-chip termination	ry pair can be configured as receiver or transmitter (OCT) -ended LVTTL/LVCMOS interfacing				
External Memory Interface	Hard memory controller— DDR4, DDR3, and DDR3L support DDR4—speeds up to 1,200 MHz/2,400 Mbps DDR3—speeds up to 1,067 MHz/2,133 Mbps Soft memory controller—provides support for RLDRAM 3 ⁽²⁾ , QDR IV ⁽²⁾ , and QDR II+ continued continued					



Feature		Description
Low-power serial transceivers	- Intel Arria 10 GT- Backplane support: - Intel Arria 10 GX- Intel Arria 10 GT- Extended range dow ATX transmit PLLs w Electronic Dispersion module Adaptive linear and of	—1 Gbps to 17.4 Gbps —1 Gbps to 25.8 Gbps —up to 12.5
HPS (Intel Arria 10 SX devices only)	Processor and system	Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability 256 KB on-chip RAM and 64 KB on-chip ROM System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers Security features—anti-tamper, secure boot, Advanced Encryption Standard (AES) and authentication (SHA) ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage
	External interfaces	Hard memory interface—Hard memory controller (2,400 Mbps DDR4, and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) flash controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller Communication interface— 10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)
	Interconnects to core	High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller
Configuration	Enhanced 256-bit ad	comprehensive design protection to protect your valuable IP investments dvanced encryption standard (AES) design security with authentication obtocol (CvP) using PCIe Gen1, Gen2, or Gen3
		continued

 $^{^{(2)}}$ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Feature	Description
	 Dynamic reconfiguration of the transceivers and PLLs Fine-grained partial reconfiguration of the core fabric Active Serial x4 Interface
Power management	SmartVID Low static power device options Programmable Power Technology Intel Quartus Prime integrated power analysis
Software and tools	 Intel Quartus Prime design suite Transceiver toolkit Platform Designer system integration tool DSP Builder for Intel FPGAs OpenCL™ support Intel SoC FPGA Embedded Design Suite (EDS)

Related Information

Intel Arria 10 Transceiver PHY Overview

Provides details on Intel Arria 10 transceivers.

Intel Arria 10 Device Variants and Packages

Table 4. **Device Variants for the Intel Arria 10 Device Family**

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	 FPGA featuring: 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. 25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line	
		GX 570	GX 660	GX 900	GX 1150
Logic Elements	s (LE) (K)	570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precision DSP Block		1,523	1,687	1,518	1,518
18 x 19 Multip	lier	3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Trai	nsceiver	48	48	96	96
GPIO (3)		696	696	768	768
LVDS Pair (4)		324	324	384	384
PCIe Hard IP E	Block	2	2	4	4
Hard Memory	Controller	16	16	16	16

Package Plan

Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)				F27 mm × 27 n 72-pin FBG/		F29 (29 mm × 29 mm, 780-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O LVDS I/O XCVR			3 V I/O	LVDS I/O	XCVR
GX 160	48	192	6	48	192	12	48	240	12
GX 220	48	192	6	48	192	12	48	240	12
GX 270	_	_	_	48	192	12	48	312	12
GX 320	_	_	_	48	192	12	48	312	12
GX 480	_	_	_	_	_	_	48	312	12



Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)		F35 (35 mm × 35 mm, 1152-pin FBGA)		KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	_	_	_	_	_	_
GX 320	48	336	24	48	336	24	_	_	_	_	_	_
GX 480	48	444	24	48	348	36	_	_	_	_	_	-
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	_	504	24	_	_	_	_	_	_	_	600	48
GX 1150	_	504	24	_	_	_	_	_	_	_	600	48

Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)		NF45 (45 mm × 45 mm) 1932-pin FBGA)		SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 900	_	342	66	_	768	48	-	624	72	_	480	96
GX 1150	_	342	66	_	768	48	ı	624	72	ı	480	96

Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 GT

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block		nput and Output ons Operator	18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode Mode	Summed with 36 bit Input
AIntel Arria 10	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
GI	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Intel Arria 10 Devices

Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices

	Product	M2	20K	ML	Total RAM Bit	
Variant	Line	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32-bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened high-performance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

External Memory Interface Spec Estimator

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.



Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	_	533
	Quarter rate	_	800

Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 (11)	Quarter rate	1,200
QDR IV SRAM ⁽¹¹⁾	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

⁽¹¹⁾ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



PMA Features

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.





PCS	Description
Standard PCS	 Operates at a data rate up to 12 Gbps Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.
Enhanced PCS	 Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA Handles data transfer to and from the FPGA fabric Handles data transfer internally to and from the PMA Provides frequency compensation Performs channel bonding for multi-channel low skew applications
PCIe Gen3 PCS	 Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates Provides support for PIPE 3.0 features Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed

Related Information

- PCIe Gen1, Gen2, and Gen3 Hard IP on page 26
- Interlaken Support on page 26
- 10 Gbps Ethernet Support on page 26

PCS Protocol Support

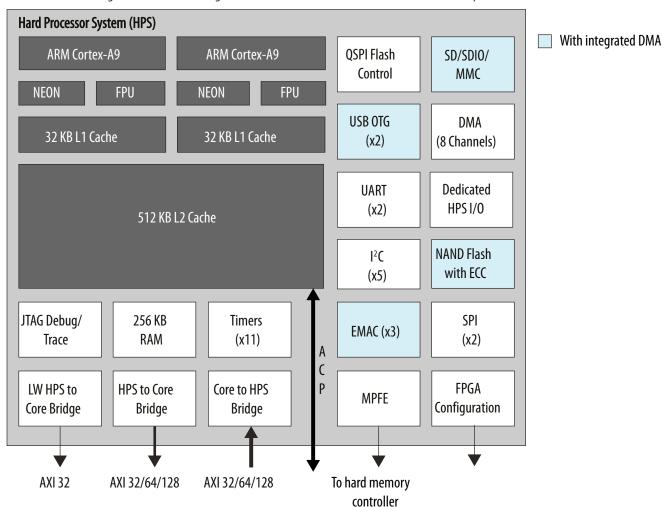
This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS
10GBASE-R	10.3125	Native PHY	Enhanced PCS
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS
10G SDI	10.692	Native PHY	Enhanced PCS
	•		continued



Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



Key Advantages of 20-nm HPS

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
 - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit
 Thumb instructions, and 8-bit Java byte codes in Jazelle style
 - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
 - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
 - 32 KB of L1 instruction cache, 32 KB of L1 data cache
 - Single- and double-precision floating-point unit and NEON media engine
 - CoreSight debug and trace technology
 - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I²C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI $^{\text{\tiny M}}$) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows
 the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is
 primarily used for control and status register (CSR) accesses to peripherals in the
 FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux*, VxWorks*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
 - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
 - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

Enhanced Configuration and Configuration via Protocol

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security ⁽¹ 4)	Partial Reconfiguration (15)	Remote System Update
JTAG	1 bit	33	33	_	_	Yes ⁽¹⁶⁾	_
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes ⁽¹⁶⁾	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes ⁽¹⁶⁾	Parallel Flash Loader (PFL) IP core
	continued					ntinued	

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁶⁾ Partial configuration can be performed only when it is configured as internal host.



September 2017 July 2017 July 2017 May 2017	2017.09.20 2017.07.13 2017.07.06 2017.05.08	 Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from Sample Ordering Core and Available Options for Intel Arria 10 GT Devices figure. Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps. Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from PMA Features of the Transceivers in Intel Arria 10 Devices table. Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family.
July 2017 July 2017	2017.07.13	1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family.
July 2017	2017.07.06	available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family.
•		· · · · · · · · · · · · · · · · · · ·
May 2017	2017.05.08	
		 Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants. Removed all "Preliminary" marks.
March 2017	2017.03.15	 Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices. Rebranded as Intel.
October 2016	2016.10.31	 Removed package F36 from Intel Arria 10 GX devices. Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.
May 2016	2016.05.02	 Updated the FPGA Configuration and HPS Booting topic. Remove V_{CC} PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices. Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA. Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.
February 2016	2016.02.11	 Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally. Revised the state for Core clock networks in the Summary of Features topic. Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table. Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table. Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table. Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure. Changed transceiver parameters in the "Low Power Serial Transceivers" section. Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table. Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure. Changed the datarates for GT devices in the "PMA Features" section. Changed the datarates for GT devices in the "PCS Features" section.



Date	Version	Changes
December 2015	2015.12.14	Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.
		Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.
November 2015	2015.11.02	• Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.
		Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in Number of Multipliers in Intel Arria 10 Devices table.
		 Updated the available options for Arria 10 GX, GT, and SX. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	Added support for 13.5G JESD204b in the Summary of Features table. Added support for 13.5G JESD204b in the Summary of Features table.
		Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.
		Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.
		Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.
January 2015	2015.01.23	Added floating point arithmetic features in the Summary of Features table.
		Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.
		Updated the table that lists the memory standards supported by Intel Arria 10 devices.
		 Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2. Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller.
		Added soft memory controller support for QDR IV.
		Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.
		Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.
		Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.
		Added a feature for fractional synthesis PLLs: PLL cascading.
		Updated the HPS programmable general-purpose I/Os from 54 to 62.
September 2014	2014.09.30	Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.
		Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.
		Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.
		continued

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Date	Version	Changes
August 2014	2014.08.18	Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620.
		Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table.
		Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration.
		Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller.
		Added variable precision DSP blocks support for floating-point arithmetic.
June 2014	2014.06.19	Updated number of dedicated I/Os in the HPS block to 17.
February 2014	2014.02.21	Updated transceiver speed grade options for GT devices in Figure 2.
February 2014	2014.02.06	Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps.
December 2013	2013.12.10	Updated the HPS memory standards support from LPDDR2 to LPDDR3. Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks .
December 2013	2013.12.02	Initial release.